



150kHz, 3A PWM BUCK DC/DC CONVERTER

Description

The AP1506 series are monolithic IC designed for a step-down DC/DC converter, and own the ability of driving a 3A load without external transistor. Due to reducing the number of external components, the board space can be saved easily. The external shutdown function can be controlled by logic level and then come into standby mode. The internal compensation makes feedback control have good line and load regulation without external design. Regarding protected function, thermal shutdown is to prevent over temperature operating from damage, and current limit is to prevent over current operating of the output switch. If current limit function occurred and V_{FB} is down to 0.5V below, the switching frequency will be reduced. The AP1506 series operate at a switching frequency of 150kHz thus allowing smaller sized filter components than what would be needed with lower frequency switching regulators. Other features include a guaranteed ±4% tolerance on output voltage under specified input voltage and output load conditions, and ±15% on the oscillator frequency. The output version included fixed 3.3V, 5V, 12V, and an adjustable type. The packages are available in a standard 5-lead TO263-5, TO220-5 and TO220-5 (R).

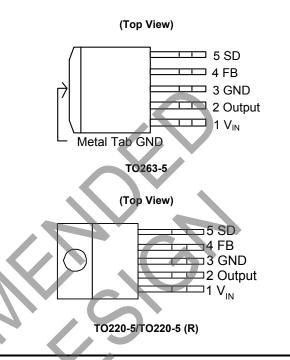
Features

- Output Voltage: 3.3V, 5V, 12V and Adjustable Output Version
- Adjustable Version Output Voltage Range, 1.23V to 18V+4%
- 150kHz +15% Fixed Switching Frequency
- Voltage Mode Non-Synchronous PWM Control
- Thermal-Shutdown and Current-Limit Protection
- ON/OFF Shutdown Control Input
- Operating Voltage can be up to 22V
- Output Load Current: 3A
- Low Power Standby Mode
- Built-in Switching Transistor On Chip
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 - 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Assignments



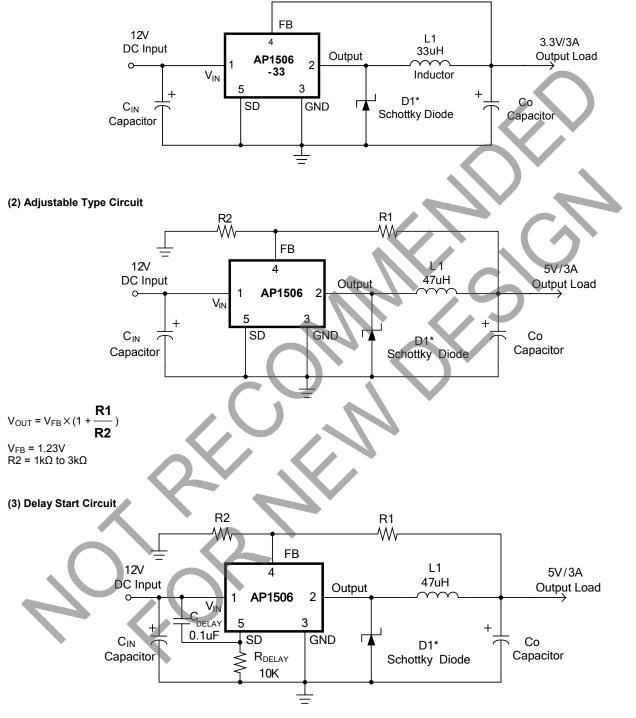
Applications

- Simple High-Efficiency Step-Down Regulator
- On-Card Switching Regulators
- Positive to Negative Converter



Typical Application Circuit

(1) Fixed Type Circuit



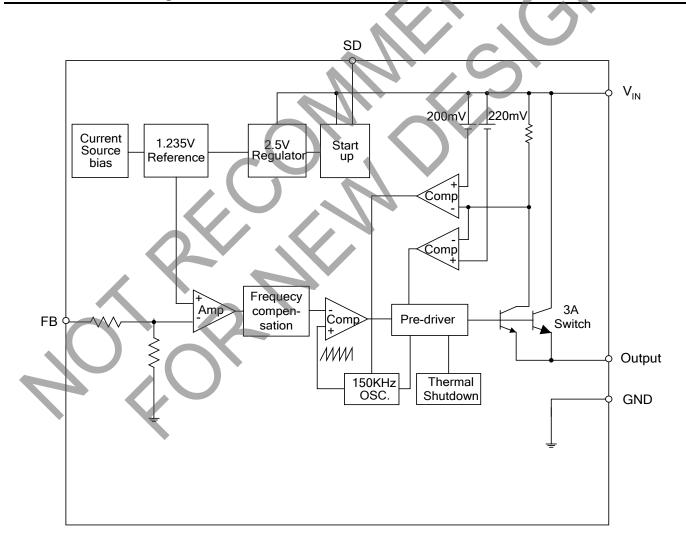
Note: For up to $2A = DFLS230L (V_F = 0.42V)$ For up to $3A = B340LA, B340LB (V_F = 0.45V)$



Pin Descriptions

Pin Number	Pin Name	Description
1	V _{IN}	Operating Voltage Input
2	Output	Switching Output
3	GND	Ground
4	FB	Output Voltage Feedback Control
5	SD	ON/OFF Shutdown

Functional Block Diagram





Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
ESD MM	Machine Model ESD Protection	400	V	
V _{CC}	Supply Voltage	+24	V	
V _{SD}	SD Pin Input Voltage	-0.3 to +18	V	
V _{FB}	FB Pin Voltage	-0.3 to +18	V	
Vout	Output Voltage to Ground	-1	V	
PD	Power Dissipation	Internally Limited	W	
T _{ST}	Storage Temperature	-65 to +150	°C	
T _{OP}	Operating Junction Temperature	-40 to +125	°C	

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V _{OP}	Operating Voltage	4.5	22	V
T _A	Operating Ambient Temperature	-20	+85	°C



Electrical Characteristics (All Output Voltage Versions)

Unless otherwise specified, V_{IN} = 12V for 3.3V, 5V, adjustable version and V_{IN} = 18V for the 12V version. I_{LOAD} = 0.5A. Specifications with **boldface type** are for full operating temperature range, the other type are for T_J = +25°C.

Symbol	Para	ameter	Conditions	Min	Тур	Max	Unit	
I _{FB}	Feedback Bias Current		V _{FB} = 1.3V (Adjustable version only)	_	-10	-50 -100	nA	
f _{OSC}	Oscillator Frequer	ncy	_	127 110	150 —	173 173	kHz	
f _{SCP}	Oscillator Frequer Protection	ncy of Short Circuit	When current limit occurred and V _{FB} $< 0.5V$, T _A = +25°C	10	30	50	kHz	
Vsat	Saturation Voltage		I _{OUT} = 3A No outside circuit V _{FB} = 0V force driver on	$\langle \langle \rangle$	1.4	1.6 1.7	V	
DC	Max. Duty Cycle (· · ·	V_{FB} = 0V force driver on V_{FB} = 12V force driver off		100 0		%	
IcL	Min. Duty Cycle (OFF) Current Limit		Peak current No outside circuit V _{FB} = 0 force driver on	3.6	4.5	5.5 6.5	А	
١L	Output = 0V	Output Leakage	No outside circuit V _{FB} = 12V force driver off) –	-200	μA	
_	Output = -1V	Current	V _{IN} = 22V	-/	-5	_	mA	
lq	Quiescent Current		V _{FB} = 12V force driver off		5	10	mA	
I _{STBY}	Standby Quiescer	nt Current	SD pin = 5V V _{IN} = 22V	_	70	150 200	μΑ	
VIL			Low (Regulator ON)	0	_	0.6		
V _{IH}	SD Pin Logic Input Threshold Voltage		High (Regulator OFF)	2.0	_	V _{IN} (Note 5)	V	
Iн	SD Pin Logic Input Current		V _{LOGIC} = 2.5V (OFF)	_	_	-0.01		
١L	SD Pin Input Current		$V_{LOGIC} = 0.5V$ (ON)		-0.1	-1	μA	
A.v.	θια		TO263-5 (Note 4)	_	37	—	°C/W	
€JA			TO220-5 (R) (Note 4)	—	31	—	C/VV	
θ _{JC}	Thermal Resistan	ce Junction to	TO263-5 (Note 4)	_	6		°C/W	
V JC	e _{JC} Case		TO220-5 (R) (Note 4)	—	5	—	0/11	

Notes: 4. Test condition: Device mounted with copper area of approximately 3 inch², no air flow. 5. Maximum voltage applied to V_{SD} is the lower of V_{IN} or 16V.



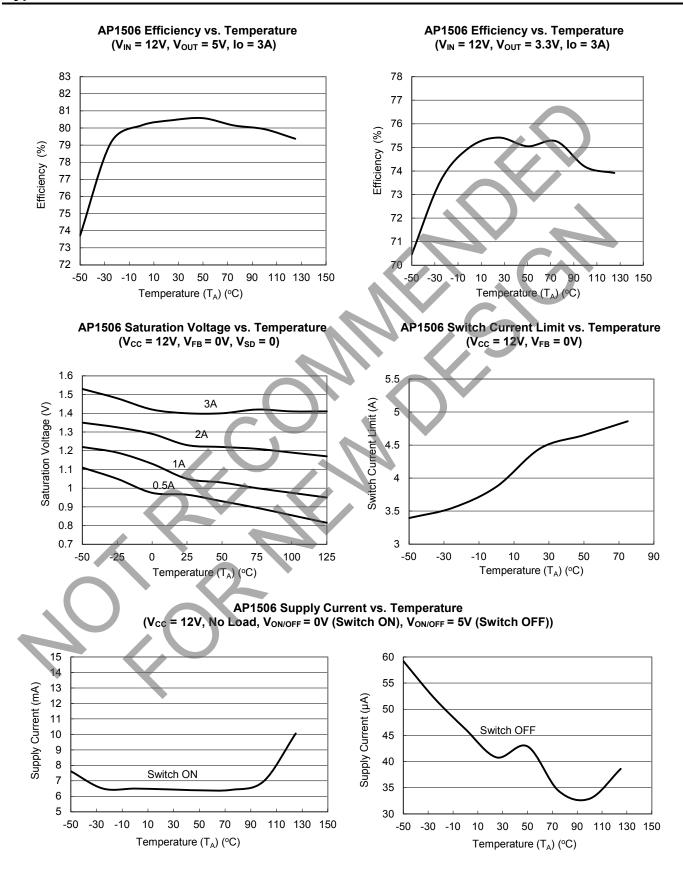
Electrical Characteristics (continued)

Specifications with **boldface** type are for full operating temperature range, the other type are for $T_J = +25^{\circ}C$.

	Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
AP1506-ADJ	V_{FB}		5V <u><</u> V _{IN} <u><</u> 22V	1.193	1.23	1.267	V
		Output Feedback	$0.2A \leq I_{LOAD} \leq 3A$ V _{OUT} programmed for 3V	1.18	_	1.28	
	η	Efficiency	V _{IN} = 12V, I _{LOAD} = 3A	—	74		%
	V _{OUT}	Output Maltana	5.5V <u><</u> V _{IN} <u><</u> 22V	3.168	3.3	3.432	V
AP1506-3.3V		Output Voltage	0.2A <u><</u> I _{LOAD} <u><</u> 3A	3.135		3.465	
	η	Efficiency	V _{IN} = 12V, I _{LOAD} = 3A	-	75	_	%
	V		8V <u><</u> V _{IN} <u><</u> 22V	4.8	5	5.2	
AP1506-5V	V _{OUT}	Output Voltage	0.2A <u><</u> I _{LOAD} <u><</u> 3A	4.75	/ _	5.25	V
	η	Efficiency	V _{IN} = 12V, I _{LOAD} = 3A		80		%
AP1506-12V	V _{OUT}	Output Voltage	15V <u><</u> V _{IN} <u><</u> 22V	11.52	12	12.48	
			0.2A ≤ I _{LOAD} ≤ 3A	11.4		12.6	V
	η	Efficiency	V _{IN} = 16V, I _{LOAD} = 3A	—	89		%

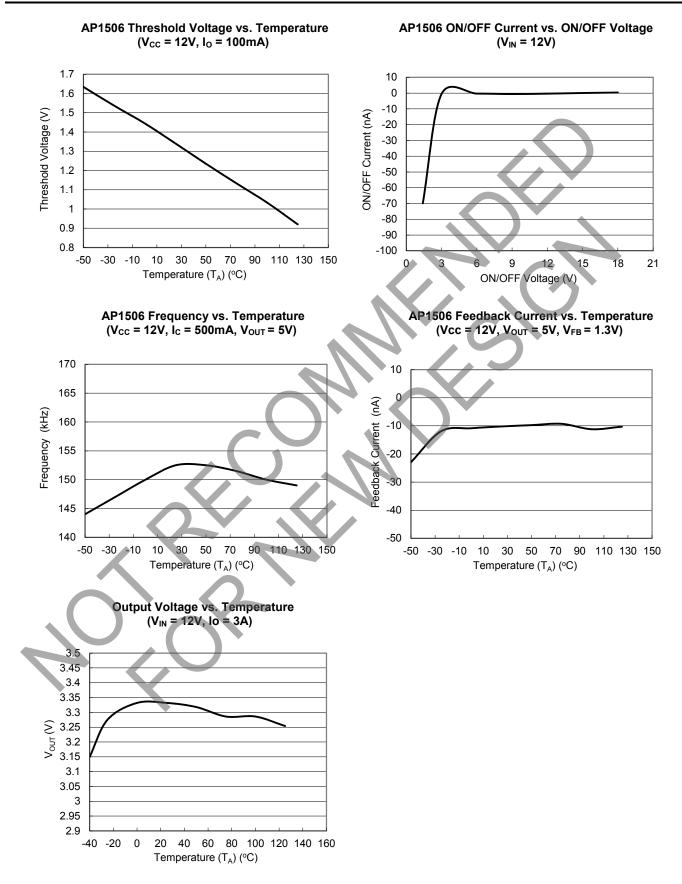


Typical Performance Characteristics





Typical Performance Characteristics (continued)





Functional Description

Pin Functions

+V_{IN}

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be presented at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

Ground

Circuit ground.

Output

Internal switch. The voltage at this pin switches between ($+V_{IN} - V_{SAT}$) and approximately -0.5V, with a duty cycle of approximately V_{OUT} / V_{IN} . To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be kept to a minimum.

Feedback (FB)

Senses the regulated output voltage to complete the feedback loop.

ON/OFF (SD)

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150µA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 18V) shuts the regulator down. If this shutdown feature is not needed, the SD pin can be wired to the ground pin.

Thermal Considerations

The TO263-5 surface mount package tab was designed to be soldering to the copper on a printed circuit board. The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PC board copper area that the package is soldered to should be at least 0.8 inch², and ideally should have 2 or more square inches of 2 oz. Additional copper area improves the thermal characteristics, but with copper areas greater than approximately 6 inch², only small improvements in heat dissipation are realized. If further thermal improvements are needed, double sided, multi-layer PC board with large copper areas and/or airflow will be recommended.

The AP1506 (TO263-5 package) junction temperature rises above ambient temperature with a 2A load for various input and output voltages. This data was taken with the circuit operating as a buck-switching regulator with all components mounted on a PC board to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but be aware that there are many factors that can affect the junction temperature. When load currents higher than 3A are used, double sided or multi-layer PC boards with large copper areas and/or airflow might be needed, especially for high ambient temperatures and high output voltages.

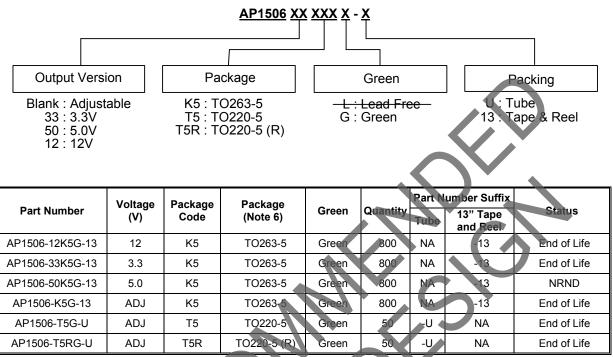
For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout (Once exception to this is the output (switch) pin, which should not have large areas of copper). Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

The TO220-5 and TO220-5 (R) package options (NRND) need a heat sink under most conditions. The size of the heat sink depends on the input voltage, the output voltage, the load current and the ambient temperature. The AP1506 junction temperature rises above ambient temperature for a 3A load and different input and output voltages. The data for these curves was taken with the AP1506 (TO220-5 and TO220-5 (R) packages) operating as a buck-switching regulator in an ambient temperature of +25°C (still air). These temperature rise numbers are all approximate and there are many factors that can affect these temperatures. Higher ambient temperatures require more heat sinking.

Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are: trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.



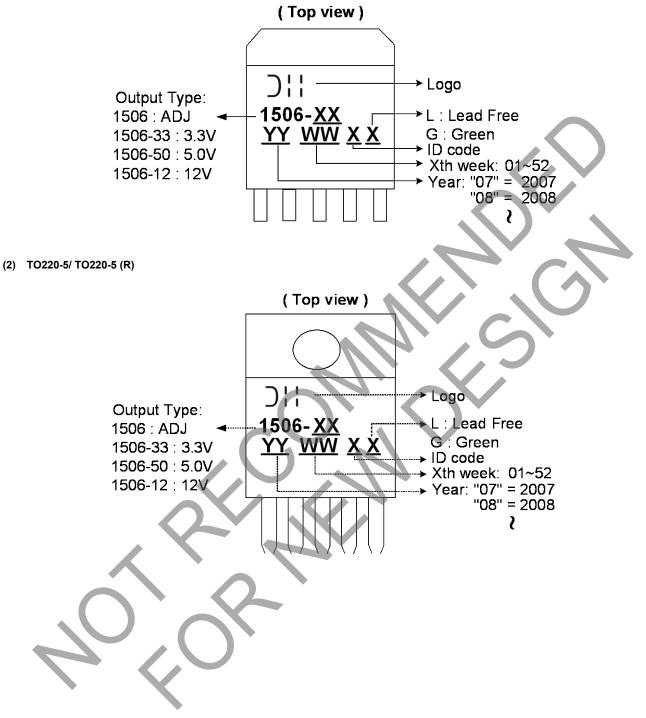
Ordering Information



Notes: 6. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

AP1506

(1) TO263-5

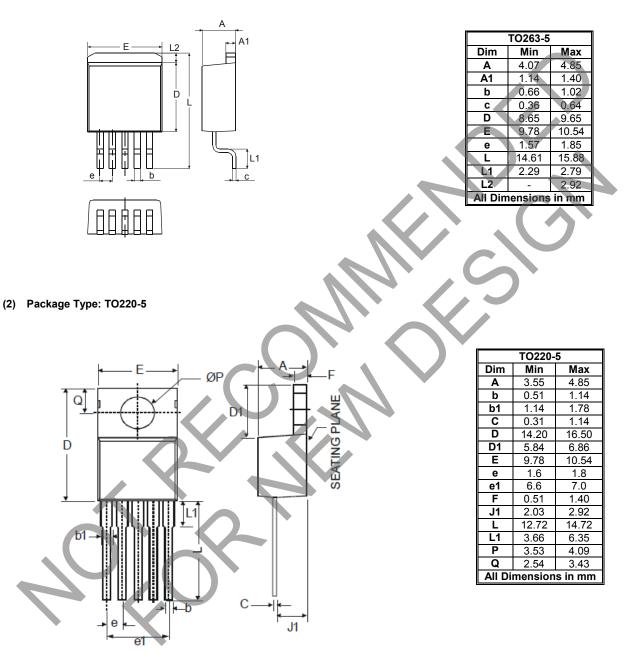




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: TO263-5

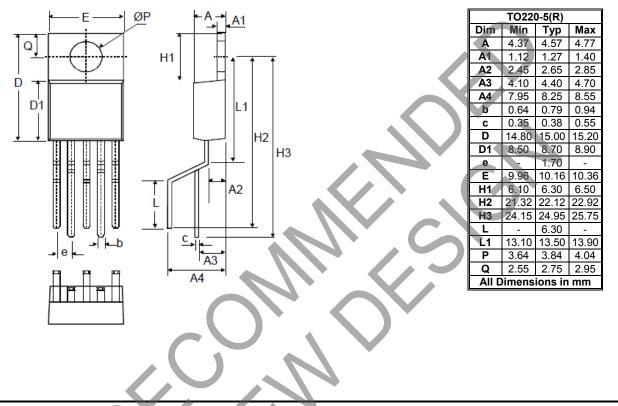




Package Outline Dimensions (continued)

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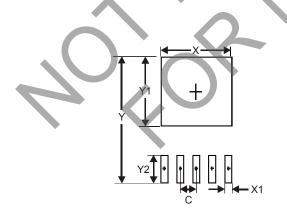
(3) Package Type: TO220-5 (R)



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: TO263-5



Dimensions	Value (in mm)
Х	10.9
X1	1.05
Y	15.7
Y1	9.1
Y2	2.5
С	1.7



AP1506

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